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JUN 16 2004

Patent

Customer No.: 31561  
Docket No. 9249-US-PA  
Application No.: 10/604,791

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Lee et al.  
Application No. : 10/604,791  
Filed : 2003/08/18  
For : SEMICONDUCTOR PACKAGE MODULE AND  
MANUFACTURING METHOD THEREOF  
Art Unit : 2811  
Examiner : NGUYEN, CUONG QUANG

OFFICE OF THE  
ASSISTANT COMMISSIONER FOR PATENTS

ASSISTANT COMMISSIONER FOR PATENTS  
Arlington, VA 22202

Dear Sirs,

In response to the Office Action, mailed on June 1, 2004, Applicant would like to elect Group II, claims 11-23, drawn to a method of making a semiconductor device, classified in class 438, subclass 100+. Please cancel Group I, claims 1-10, drawn to a semiconductor device, classified in class 257, subclass 723 without waiver, prejudice or disclaimer.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN IP Office

Date: June 16, 2004

By: Belinda Lee  
Belinda Lee  
Registration No.: 46,863

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